

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 05/28/2022

Details for "AM3357B2CZD60"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
AM3357B2CZD60	SNAGCU	Level-3-260C-168 HR	TI PHILIPPINES A/T	ZCZ   324	15x15x0.9	581.4

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	2.298442	94.962541	949625	0.395336	3953
Not Categorized	Proprietary Materials		0.000376	0.015535	155	0.000065	1
Precious Metals	Gold	7440-57-5	0.025682	1.061079	10611	0.004417	44
Precious Metals	Palladium	7440-05-3	0.095867	3.960846	39608	0.016489	165
Sub-Total			<b>2.420367</b>	<b>100</b>	<b>1000000</b>	<b>0.416307</b>	<b>4163</b>
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	5.105424	81.999998	820000	0.878142	8781
Thermoplastics	Epoxy	85954-11-6	1.120703	18.000002	180000	0.192763	1928
Sub-Total			<b>6.226127</b>	<b>100</b>	<b>1000000</b>	<b>1.070904</b>	<b>10709</b>
<b>Mold Compound</b>							
Other Inorganic Materials	Aluminum Nitride	24304-00-5	2.97526	1	10000	0.51175	5117
Other Inorganic Materials	Fused Silica	60676-86-0	252.391287	84.83	848300	43.411726	434117
Other Nonferrous Metals and Alloys	Metal Oxide	Trade Secret	3.272786	1.1	11000	0.562925	5629
Other Organic Materials	Bromine	7726-95-6	0.059505	0.02	200	0.010235	102
Other Organic Materials	Chlorine	7782-50-5	0.059505	0.02	200	0.010235	102
Other Plastics and Rubber	Carbon Black	1333-86-4	0.892578	0.3	3000	0.153525	1535
Other Plastics and Rubber	Silicone	218163-11-2	2.380208	0.8	8000	6.4094	4094
Thermoplastics	Epoxy	85954-11-6	35.494849	11.93	119300	6.105174	61052
Sub-Total			<b>297.525978</b>	<b>100</b>	<b>1000000</b>	<b>51.174969</b>	<b>511750</b>
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	9.783571	100	1000000	1.682791	16828
Sub-Total			<b>9.783571</b>	<b>100</b>	<b>1000000</b>	<b>1.682791</b>	<b>16828</b>
<b>Solder Ball</b>							
Copper and Its Alloys	Copper	7440-50-8	0.780088	0.5	5000	0.134176	1342
Nickel and Its Alloys	Nickel	7440-02-0	0.078009	0.05	500	0.013418	134
Other Nonferrous Metals and Alloys	Tin	7440-31-5	153.287311	98.25	982500	26.365675	263657
Precious Metals	Silver	7440-22-4	1.872211	1.2	12000	0.322023	3220
Sub-Total			<b>156.017619</b>	<b>100</b>	<b>1000000</b>	<b>26.835293</b>	<b>268353</b>
<b>Substrate</b>							
Ceramics / Glass	Woven Glass Fiber	65997-17-3	24.255011	22.1677	221677	4.171903	41719
Copper and Its Alloys	Copper Oxide	1317-39-1	44.748299	40.8974	408974	7.696783	76968
Nickel and Its Alloys	Nickel	7440-02-0	0.045189	0.0413	413	0.007773	78
Other Inorganic Materials	Aluminum Nitride	24304-00-5	0.05799	0.053	530	0.009974	100
Other Inorganic Materials	Aluminum Oxide	1344-28-1	11.880061	10.8577	108577	2.04339	20434
Other Inorganic Materials	Silica	7631-86-9	4.879407	4.4595	44595	0.839266	8393
Other Nonferrous Metals and Alloys	Barium Sulfate	7727-43-7	0.943166	0.862	8620	0.162226	1622
Other Plastics and Rubber	Other Filler		0.188633	0.1724	1724	0.032445	324
Precious Metals	Gold	7440-57-5	0.612401	0.5597	5597	0.105334	1053
Thermoplastics	Epoxy	85954-11-6	21.805843	19.9293	199293	3.750642	37506
Sub-Total			<b>109.416</b>	<b>100</b>	<b>1000000</b>	<b>18.819736</b>	<b>188197</b>
<b>Total</b>			<b>581.389662</b>			<b>100</b>	<b>1000000</b>

**Important Note**  
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights. See Product Content Methodology.](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.